

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q88153

Koji WATANABE, et al.

Appln. No.: 10/541,586

Group Art Unit: 1796

Confirmation No.: 1996

Examiner: Michael J FEELY

Filed: July 7, 2005

For: CURING RESIN COMPOSITION, ADHESIVE EPOXY RESIN PASTE, ADHESIVE EPOXY RESIN SHEET, CONDUCTIVE CONNECTION PASTE, CONDUCTIVE CONNECTION SHEET, AND ELECTRONIC COMPONENT JOINED BODY

AMENDMENT UNDER 37 C.F.R. § 1.111

MAIL STOP AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated August 21, 2008, please amend the above-identified application as follows on the accompanying pages.

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